



P5MND4P0



40V Dual N-Channel MOSFETs

General Description

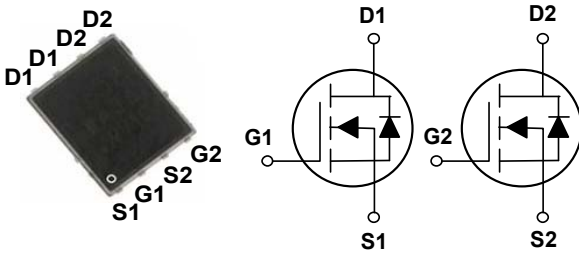
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)}$	I_D
40 V	4 m Ω (typ.)	70 A

Features

- $R_{DS(ON)}=4m\Omega(\text{typ.})@V_{GS}=10V$
- $R_{DS(ON)}=5.6m\Omega(\text{typ.})@V_{GS}=6V$
- Reliable and Rugged
- Green Device Available

PPAK5X6 Dual Pin Configuration



Applications

- Power Management in DC/DC Converters
- SMPS Synchronous Rectification

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current - Continuous	70	A
I_{DM}	Drain Current - Pulsed	140	A
I_S	Diode Continuous Forward Current	30	A
T_J	Operating Junction Temperature Range	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
Marking Code		ND4P0	

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2	$^\circ\text{C/W}$

**40V Dual N-Channel MOSFETs****Electrical Characteristics (T_J=25°C, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	40	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =32V, V _{GS} =0V	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(on)}	Static Drain-Source On-Resistance (NOTE 3)	V _{GS} =10V, I _D =2A	---	4.0	---	mΩ
		V _{GS} =6V, I _D =2A	---	5.6	---	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2	---	4	V

Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =25V, V _{GS} =10V, I _D =14A	---	53	---	nC
Q _{gs}	Gate-Source Charge		---	11.8	---	
Q _{gd}	Gate-Drain Charge		---	16.2	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =15V, V _{GS} =10V, R _{GEN} =1Ω, I _D =1A	---	28	---	ns
T _r	Rise Time		---	21	---	
T _{d(off)}	Turn-Off Delay Time		---	39	---	
T _f	Fall Time		---	19	---	
C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, F=1MHz	---	3222	---	pF
C _{oss}	Output Capacitance		---	305	---	
C _{rss}	Reverse Transfer Capacitance		---	183	---	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V _{SD}	Diode Forward Voltage (NOTE 3)	V _{GS} =0V, I _S =2A	---	---	1.1	V

NOTES :

1. Current may be limited by bonding wire.
2. The R_{θJC} is the sum of the thermal impedance from junction to case and depends on package type.
3. MOS static characteristics test by wafer level.
4. Guaranteed by design, not subject to production testing.



Characteristics Curves

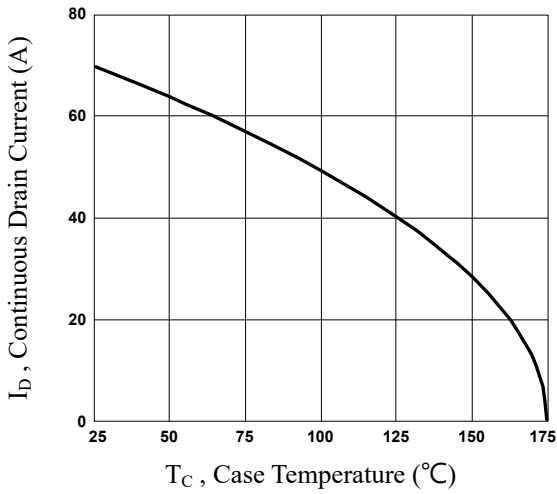


Fig.1 Continuous Drain Current vs. T_c

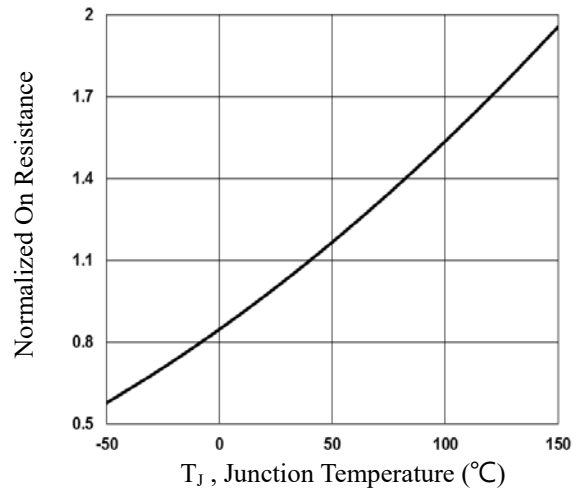


Fig.2 Normalized R_{DS(on)} vs. T_J

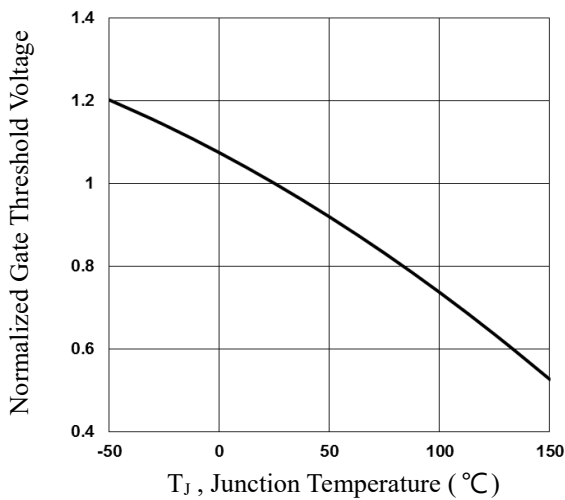


Fig.3 Normalized V_{th} vs. T_J

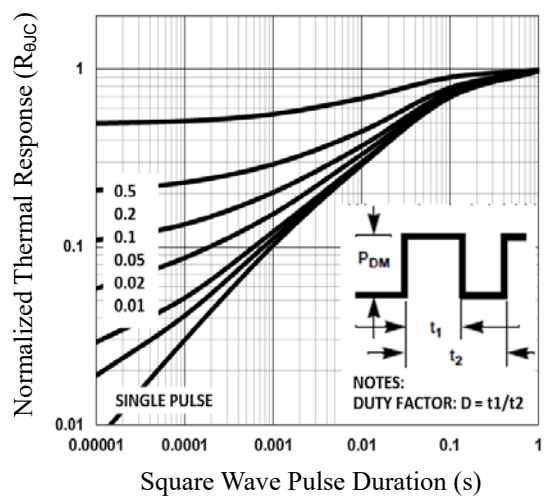


Fig.4 Normalized Transient Impedance

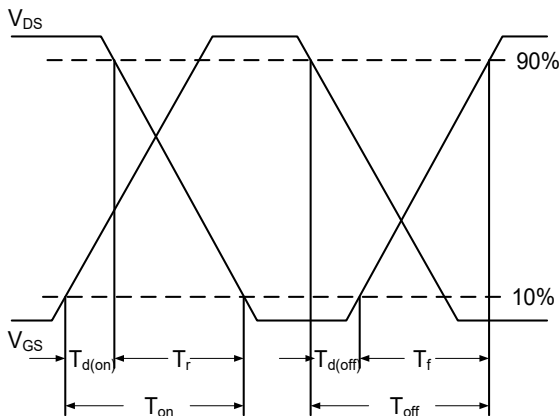


Fig.5 Switching Time Waveform

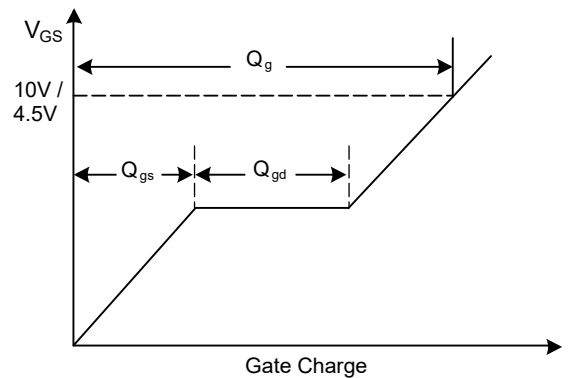


Fig.6 Gate Charge Waveform

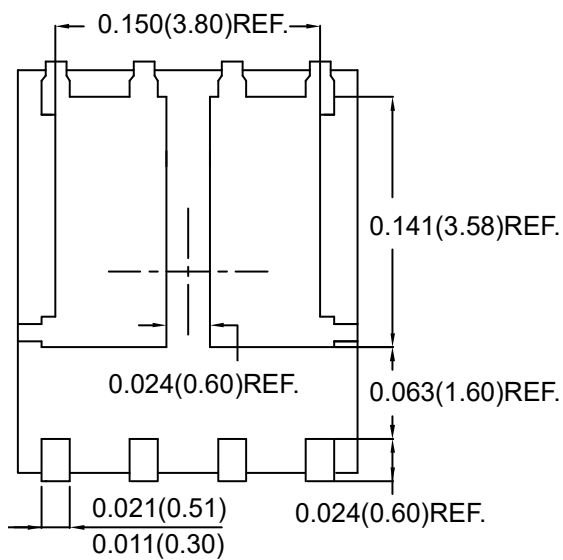
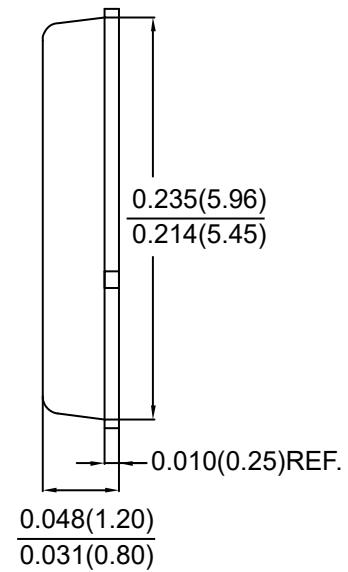
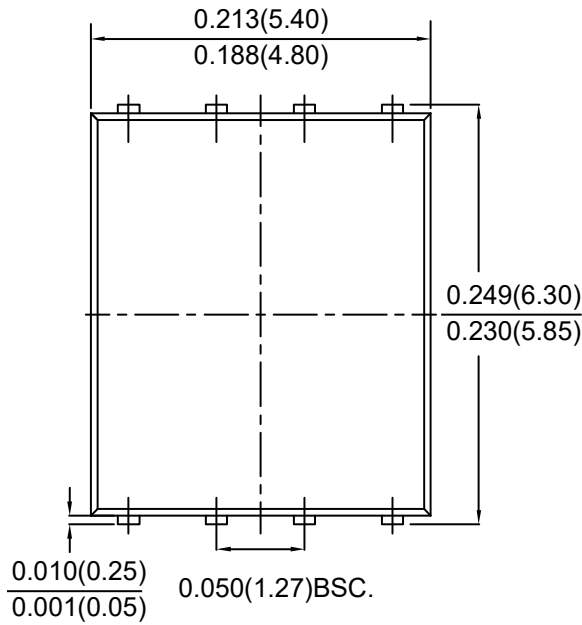


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Package Outline Dimensions



PPAK5X6 Dual

Dimensions in inches and (millimeters)



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